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MONDAY OCTOBER 15, 2018

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Session Chairs : ***Bruce Doris; IBM / Mostafa Emam; Incize***

1.1 **Enabling Market Innovation through Differentiated FDSOI Technology** N/A
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1.2 **Powering the Human Intranet** N/A
Jan Rabaey; *Co-Director of Berkeley Wireless Research Center and Director of the FCRP Multiscale Systems Research Center, University of California, Berkeley, USA (Plenary Speaker)*

1.3 **Left, Right or Up. Living in a 3D World** N/A
Joe Macri; *Corporate Vice President and Product CTO, AMD, USA (Plenary Speaker)*

SESSION 2: PLENARY II

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2.2 **Components for High-Fidelity Solid State Quantum Computers** N/A
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2.3 **Material and Device Innovation for IoT, Automotive and Mobile Connectivity Applications** N/A
Thomas Piliszczuk; *Executive Vice President, Marketing, Business Development and Global Sales, SOITEC,France (Plenary Speaker)*

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Session Chairs : ***Davood Shahrjerdi; New York Univeristy / Jin-Woo Han; NASA***